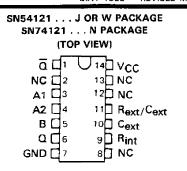
#### SDLS042

- Programmable Output Pulse Width With R<sub>int</sub>....35 ns Typ With R<sub>ext</sub>/C<sub>ext</sub>....40 ns to 28 Seconds
- Internal Compensation for Virtual Temperature Independence
- Jitter-Free Operation up to 90% Duty Cycle
- Inhibit Capability

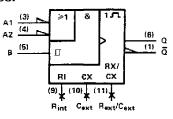
FUNCTION TABLE										
11	VPUTS	OUTPUTS								
A1	A2	в	a ā							
L	х	н	LH							
х	L	н	LT HT							
х	х	L	Lt Ht							
н	н	х	LT HT							
н	Ļ	н								
Ļ	н	н								
Ļ	i	н								
Ļ	х	t								
x	L	t								

#### SN54121, SN74121 MONOSTABLE MULTIVIBRATORS WITH SCHMITT-TRIGGER INPUTS MAY 1983 – REVISED MARCHT1988



NC - No internal connection.

logic symbol<sup>‡</sup>



<sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

For explanation of function table symbols, see page

† These lines of the function table assume that the indicated steady-state conditions at the A and B inputs have been setup long enough to complete any pulse started before the setup.

#### description

These multivibrators feature dual negative-transition-triggered inputs and a single positive-transition-triggered input which can be used as an inhibit input. Complementary output pulses are provided.

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. Schmitt-trigger input circuitry (TTL hysteresis) for the B input allows jitter-free triggering from inputs with transition rates as slow as 1 volt/second, providing the circuit with an excellent noise immunity of typically 1.2 volts. A high immunity to VCC noise of typically 1.5 volts is also provided by internal latching circuitry.

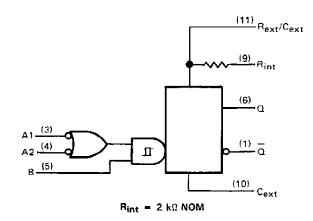
Once fired, the outputs are independent of further transitions of the inputs and are a function only of the timing components. Input pulses may be of any duration relative to the output pulse. Output pulse length may be varied from 40 nanoseconds to 28 seconds by choosing appropriate timing components. With no external timing components (i.e.,  $R_{int}$  connected to  $V_{CC}$ ,  $C_{ext}$  and  $R_{ext}/C_{ext}$  open), an output pulse of typically 30 or 35 nanoseconds is achieved which may be used as a d-c triggered reset signal. Output rise and fall times are TTL compatible and independent of pulse length.

Pulse width stability is achieved through internal compensation and is virtually independent of  $V_{CC}$  and temperature. In most applications, pulse stability will only be limited by the accuracy of external timing components.

Jitter-free operation is maintained over the full temperature and V<sub>CC</sub> ranges for more than six decades of timing capacitance (10 pF to 10  $\mu$ F) and more than one decade of timing resistance (2 k $\Omega$  to 30 k $\Omega$  for the SN54121 and 2 k $\Omega$  to 40 k $\Omega$  for the SN74121). Throughout these ranges, pulse width is defined by the relationship t<sub>W</sub>(out) = C<sub>ext</sub>R<sub>T</sub>In2  $\approx$  0.7 C<sub>ext</sub>R<sub>T</sub>. In circuits where pulse cutoff is not critical, timing capacitance up to 1000  $\mu$ F and timing resistance as low as 1.4 k $\Omega$  may be used. Also, the range of jitter-free output pulse widths is extended if V<sub>CC</sub> is held to 5 volts and free-air temperature is 25 °C. Duty cycles as high as 90% are achieved when using maximum recommended R<sub>T</sub>'. Higher duty cycles are available if a certain amount of pulse-width jitter is allowed.



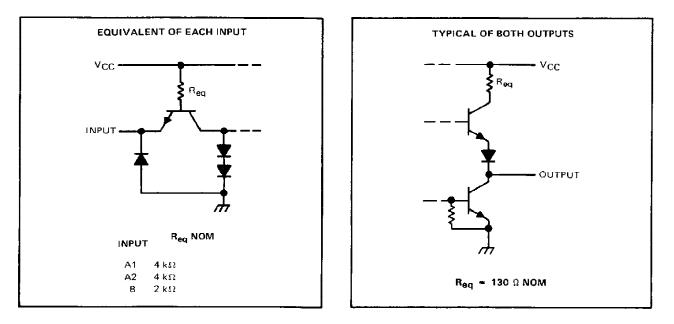
logic diagram (positive logic)



Pin numbers shown on logic notation are for J or N packages.

NOTES: 1. An external capacitor may be connected between C<sub>ext</sub> (positive) and H<sub>ext</sub>/C<sub>ext</sub>.
 2. To use the internal timing resistor, connect R<sub>int</sub> to V<sub>CC</sub>. For improved pulse width accuracy and repeatability, connect an external resistor between R<sub>ext</sub>/C<sub>ext</sub> and V<sub>CC</sub> with R<sub>int</sub> open-circuited.

#### schematics of inputs and outputs





## SN54121, SN74121 Monostable Multivibrators With Schmitt-Trigger inputs

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 3)	· · · · · · · · · · · · · · · · · · ·
Input voltage	
Operating free-air temperature range:	SN54121
	SN74121 0°C to 70°C
Storage temperature range	

NOTE 3: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

				MIN	NOM	MAX	UNIT
Vcc	Supply voltage		54 Family	4.5	5	5.5	v
•	Low-level output current Rate of rise or fall of input pulse nput pulse width External timing capacitance		74 Family	4.75	5	5.25	v
юн	High-level output current					-0.4	mΑ
10L	Low-level output current					16	mA
du/dt	dv/dt Rate of rise or fall of input pulse	Schmitt input, B Logic inputs, A1, A2		1			V/s
				1			V/µs
t <sub>w(in)</sub>	input pulse width			50			ns
Rext	External timing canacitance	S4 Family		1.4		30	
''ext	External timing capacitance		74 Family	1.4	40		kΩ
C <sub>ext</sub>	External timing capacitance			0		1000	μF
	Duty evelo	$R_{T} = 2 k\Omega$				67	
		$R_T = MAX R_{ext}$				90	%
Тд	Operating free-air temperature		54 Family	- 55		125	
'A	operating nee-on temperature		74 Family	0		70	٥C



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	MIN	TYP‡	MAX	UNIT	
VIH	High-level input voltage at B input	V <sub>CC</sub> = MIN		2			V
VIL	Low-level input voltage at A input	Vcc - MIN	1.1			0.8	v
VT+	Positive-going threshold voltage at B input	VCC = MIN			1.55	2	V
VT-	Negative-going threshold voltage at B input	V <sub>CC</sub> = MIN		0.8	1.35		V
Vik	Input clamp voltage	$V_{CC} = MIN,$	l <sub>t</sub> = −12 mA			- 1.5	V
юн	High-level output voltage	V <sub>CC</sub> ≃ MIN,	OH = MAX	2.4	3.4		V
VOL	Low-level output voltage	$V_{CC} = MIN,$	IOL = MAX		0.2	0.4	V
Ι	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V			1	mÅ
		V <sub>CC</sub> = MAX,	A1 or A2			40	
ήH	High-level input current	V <sub>1</sub> - 2.4 V	В			80	μA
		VCC = MAX,	A1 or A2			- 1.6	4
μL	Low-level input current	Vj = 0.4 V	В			- 3.2	mΑ
	Short-circuit output current <sup>§</sup>		54 Family	- 20		- 55	mA
los	Short-circuit output content*	$V_{CC} = MAX$	74 Family	- 18		- 55	01A
	Supply supprt		Quiescent		13	25	A
ICC	Supply current	$V_{CC} = MAX$	Triggered	2:		40	mA

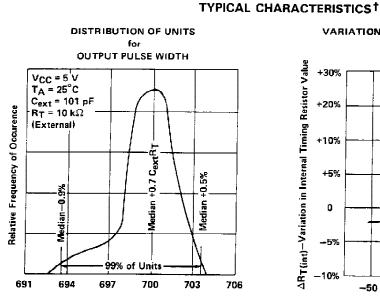
<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25 \text{ °C}$ . <sup>†</sup>Not more than one output should be shorted at a time.

#### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C

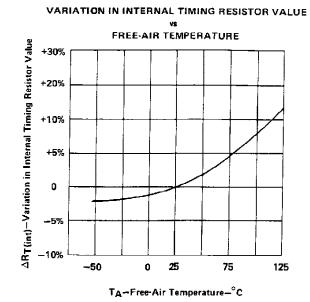
	PARAMETER	TEST CON	DITIONS	MIN	түр	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high- level Q output from either A input				45	70	ns
tplh	Propagation delay time, low-to-high- level Q output from B input		C <sub>ext</sub> = 80 pF,		35	55	ns
tphl	Propagation delay time, high-to-low level Q output from either A input	C <sub>I</sub> = 15 pF,	R <sub>int</sub> to V <sub>CC</sub>		50	80	пs
<sup>t</sup> PHL	Propagation delay time, high-to-low level $\overline{\Omega}$ output from 8 input	$R_{L} = 400 \Omega,$ See Note 4			40	65	ns
tw(out)	Pulse width obtained using internal timing resistor		$C_{ext} = 80 \rho F,$ $R_{int}$ to VCC	70	110	150	ns
tw(out)	Pulse width obtained with zero timing capacitance		C <sub>ext</sub> = 0, R <sub>int</sub> to VCC		30	50	ns
•	Pulse width obtained using		$C_{ext} = 100 \text{ pF},$ $R_T = 10 \text{ k}\Omega$	600	700	800	ns
<sup>t</sup> w(out)	external timing resistor		C <sub>ext</sub> = 1 μF, F <sub>T</sub> = 10 kΩ	6	7	8	ms

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

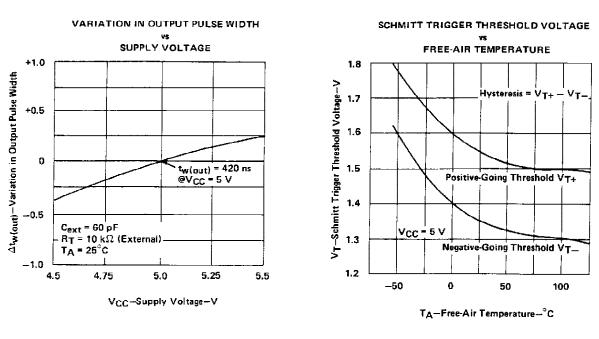


tw(out)-Output Pulse Width-ns





#### **FIGURE 2**

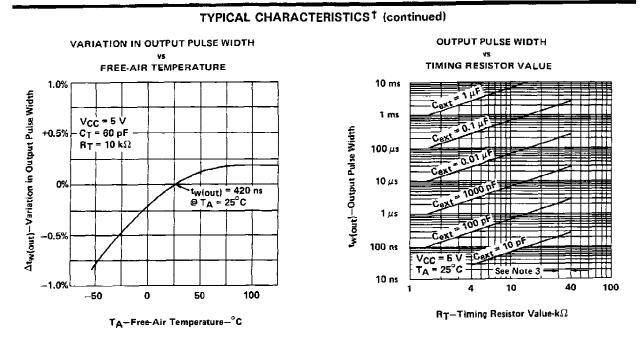


#### FIGURE 3

**FIGURE 4** 

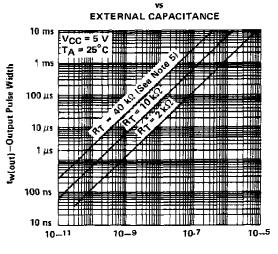
<sup>†</sup>Data for temperatures below 0°C and above 70°C are applicable for SN54121.





**FIGURE 5** 





OUTPUT PULSE WIDTH



#### FIGURE 7

NOTE 5: These values of resistance exceed the maximum recommended use over the full temperature range of the SN54121. 
<sup>†</sup>Data for temperatures below 0°C and above 70°C are applicable for SN54121.

TEXAS VI INSTRUMENTS

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TEXAS INSTRUMENTS

23-Apr-2005

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finisl	n MSL Peak Temp <sup>(3)</sup>
5962-9755301QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9755301QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9755301QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74121D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74121N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74121N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74121N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74121NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121WA	ACTIVE	CFP	WA	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121WA	ACTIVE	CFP	WA	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



## PACKAGE OPTION ADDENDUM

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J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



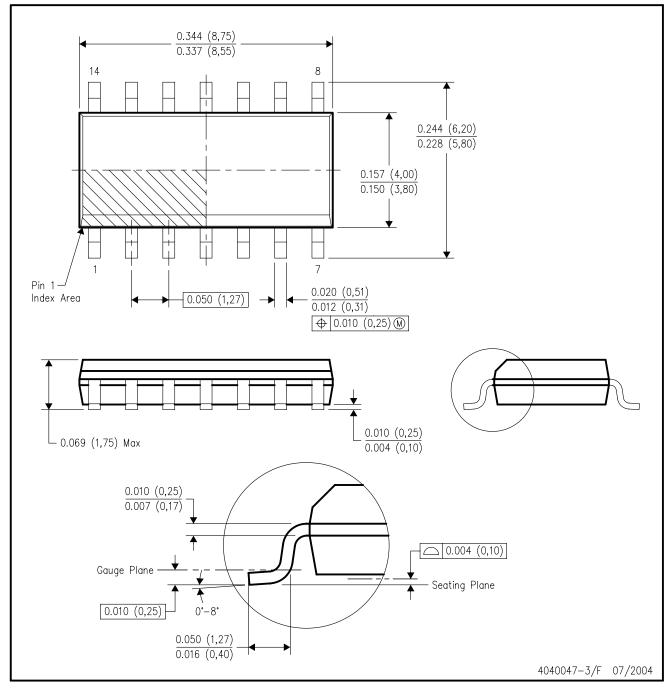
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



## MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9755301QCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755301QC A SNJ54121J	Samples
5962-9755301QDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755301QD A SNJ54121W	Samples
SN54121J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54121J	Samples
SN74121D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74121	Samples
SN74121DE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74121	Samples
SN74121N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74121N	Samples
SNJ54121J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755301QC A SNJ54121J	Samples
SNJ54121W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755301QD A SNJ54121W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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## PACKAGE OPTION ADDENDUM

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54121, SN74121 :

- Catalog : SN74121
- Military : SN54121

#### NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## TEXAS INSTRUMENTS

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9-Aug-2022

## TUBE



## - B - Alignment groove width

#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9755301QDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74121D	D	SOIC	14	50	506.6	8	3940	4.32
SN74121DE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74121N	N	PDIP	14	25	506	13.97	11230	4.32
SN74121N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54121W	W	CFP	14	1	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14



# **GENERIC PACKAGE VIEW**

# CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



# J0014A



# **PACKAGE OUTLINE**

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



# J0014A

# **EXAMPLE BOARD LAYOUT**

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
   E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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